



**WHAT IS CLAIMED IS:**

- 1 1. A method of forming a conductive device, the method  
2 comprising:  
3 forming a conductive layer on a substrate;  
4 etching the conductive layer to form a plurality of conductive traces;  
5 etching the conductive layer to form at least one mask feature; and  
6 removing substrate material that is not covered by the at least one  
7 mask feature so as to form at least one mechanical alignment feature.
- 1 2. The method of claim 1 wherein the etching steps are  
2 performed simultaneously.
- 1 3. The method of claim 1 wherein the removing step includes  
2 removing the substrate material with a laser.
- 1 4. The method of claim 1 wherein the removing step includes  
2 removing the substrate material so as to form at least one aperture.
- 1 5. The method of claim 1 wherein the removing step includes  
2 removing the substrate material so as to form at least one side edge.
- 1 6. The method of claim 1 wherein the removing step includes  
2 removing the substrate material so as to form at least one tab.
- 1 7. The method of claim 1 wherein the removing step includes  
2 removing the substrate material so as to form at least one slot.
- 3 8. A conductive device produced according to the method of  
4 claim 1.
- 1 9. A method of forming a printed circuit board, the method  
2 comprising:

3 forming a conductive layer on a substrate;  
4 etching the conductive layer to form multiple conductive traces,  
5 each trace having a contact portion,  
6 etching the conductive layer to form multiple mask features that  
7 cooperate to define a template; and  
8 ablating with a laser substrate material that is not covered by the  
9 template so as to form a plurality of mechanical alignment features.

1 10. The method of claim 9 wherein the etching steps are  
2 performed simultaneously.

Sub A1  
1 11. The method of claim 9 wherein the ablating step comprises  
2 ablating substrate material so as to form a multiple apertures and multiple side  
3 edges, wherein the apertures and the side edges function as mechanical alignment  
4 features.

Sub B1  
1 12. A printed circuit board produced according to the method of  
2 claim 9.

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A2